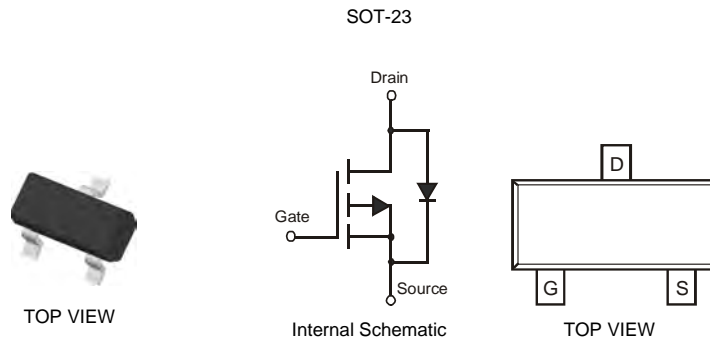


Features

- Low On-Resistance
 - 80 mΩ @ $V_{GS} = -4.5V$
 - 100 mΩ @ $V_{GS} = -2.5V$
 - 140 mΩ @ $V_{GS} = -1.8V$
- Very Low Gate Threshold Voltage $V_{GS(th)} \leq 1V$
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/ROHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q 101 Standards for High Reliability**

Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.008 grams (approximate)



Maximum Ratings @ $T_A = 25^\circ C$ unless otherwise specified

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Drain Current (Note 3)	I_D	$T_A = 25^\circ C$	-3.2
		$T_A = 70^\circ C$	-2.5
Pulsed Drain Current	I_{DM}	-13	A

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 3)	P_D	1.4	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	90	$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on 1in² FR-4 PCB with 2 oz. Copper. $t \leq 10$ sec.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1.0	μA	V _{DS} = -16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100 ±800	nA	V _{GS} = ±8V, V _{DS} = 0V V _{GS} = ±12V, V _{DS} = 0V
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	V _{GS(th)}	-0.4	-0.6	-0.9	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	60	80	mΩ	V _{GS} = -4.5V, I _D = -1.5A
			73	100		V _{GS} = -2.5V, I _D = -1.2A
			92	140		V _{GS} = -1.8V, I _D = -1.2A
Forward Transconductance	g _{FS}	—	7	—	S	V _{DS} = -10V, I _D = -1.5A
Diode Forward Voltage (Note 4)	V _{SD}	—	—	-1.0	V	V _{GS} = 0V, I _S = -1.0A
DYNAMIC CHARACTERISTICS (Note 5)						
Input Capacitance	C _{iSS}	—	627	—	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oSS}	—	64	—	pF	
Reverse Transfer Capacitance	C _{rSS}	—	53	—	pF	V _{GS} = 0V, V _{DS} = 0V, f = 1.0MHz
Gate Resistance	R _G	—	44.9	—	Ω	
Total Gate Charge	Q _g	—	6.5	—	nC	V _{GS} = -4.5V, V _{DS} = -10V, I _D = -3A
Gate-Source Charge	Q _{gs}	—	0.9	—	nC	
Gate-Drain Charge	Q _{gd}	—	1.5	—	nC	
Turn-On Delay Time	t _{D(on)}	—	12.5	—	ns	V _{DS} = -10V, V _{GS} = -4.5V, R _L = 10Ω, R _G = 1.0Ω, I _D = -1A
Turn-On Rise Time	t _r	—	10.3	—	ns	
Turn-Off Delay Time	t _{D(off)}	—	46.5	—	ns	
Turn-Off Fall Time	t _f	—	22.2	—	ns	

Notes: 4. Short duration pulse test used to minimize self-heating effect.
5. Guaranteed by design. Not subject to product testing.

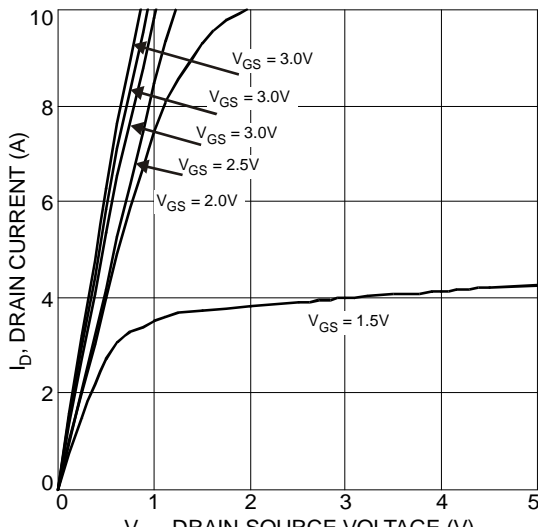


Fig. 1 Typical Output Characteristics

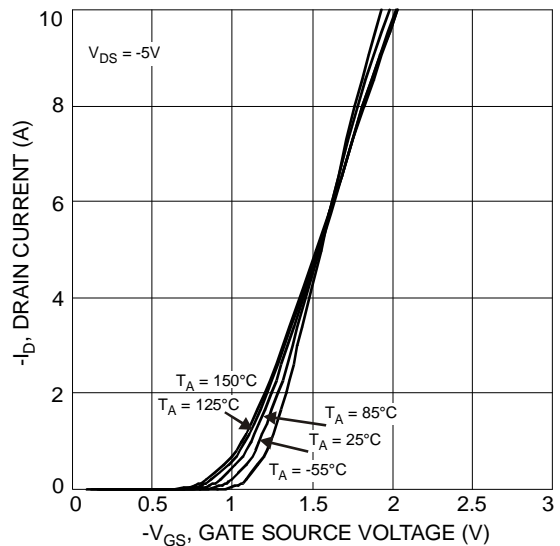


Fig. 2 Typical Transfer Characteristics

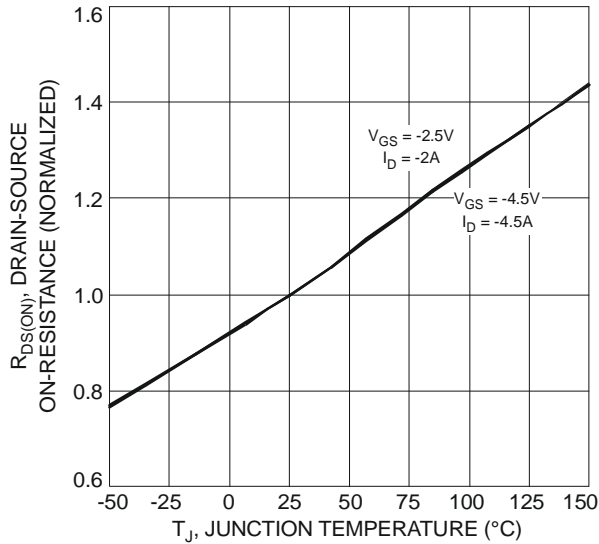


Fig. 3 On-Resistance Variation with Temperature

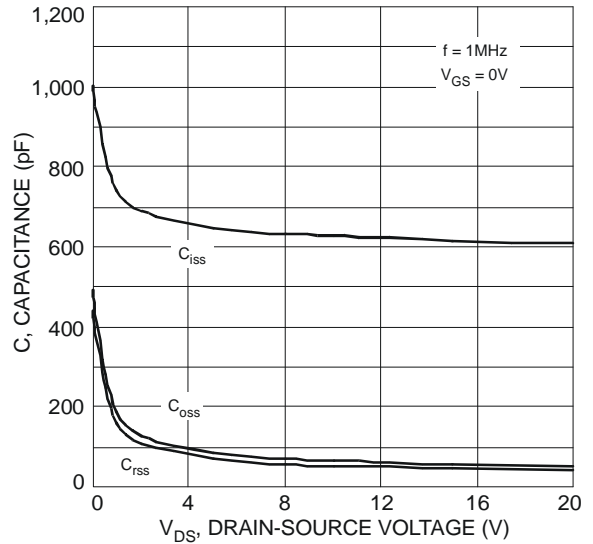


Fig. 4 Typical Capacitance

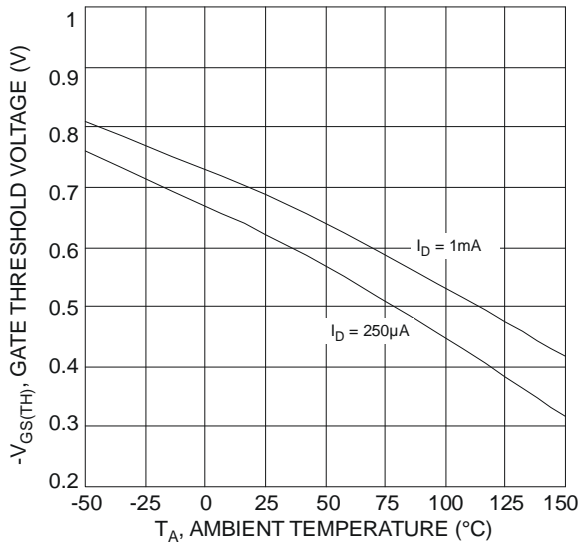


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

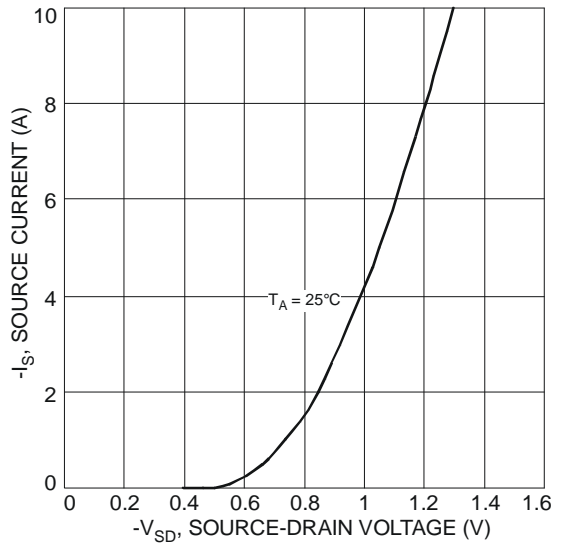


Fig. 6 Diode Forward Voltage vs. Current

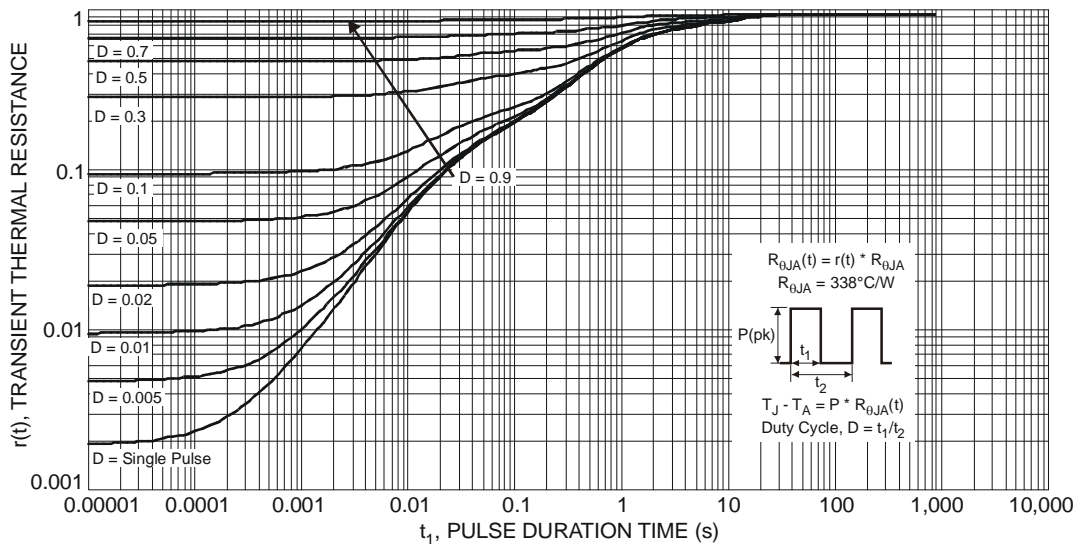


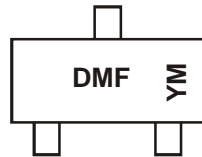
Fig. 7 Transient Thermal Response

Ordering Information (Note 6)

Part Number	Case	Packaging
DMP2160U-7	SOT-23	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



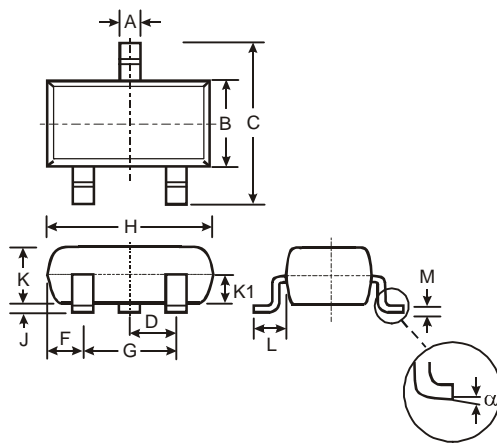
DMF = Marking Code
 YM = Date Code Marking
 Y = Year (ex: V = 2008)
 M = Month (ex: 9 = September)

Date Code Key

Year	2008	2009	2010	2011	2012	2013	2014	2015
Code	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

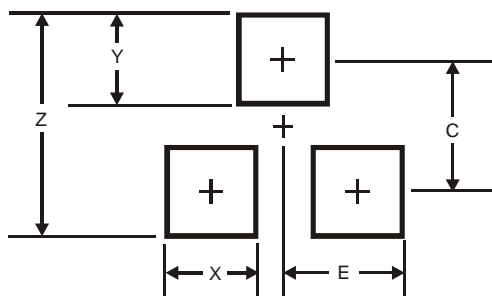
Package Outline Dimensions



SOT-23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-

All Dimensions in mm

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

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